



Final Product Change Notification

202201008F01 : i.MX RT1024 Fab Site Transfer from SMIC8 to SMICB2 with New Silicon Revision

Note: This notice is NXP Company Proprietary.

Issue Date: Mar 21, 2022 **Effective date:** Jun 19, 2022

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For detailed information we invite you to view this notification online

Management summary

Wafer Fabrication site transfer for the i.MX RT1024 to the SMICB2, Beijing, China Wafer Fabrication site.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input checked="" type="checkbox"/> Other: data sheet			

PCN Overview

Description

NXP Semiconductors announces the Wafer Fabrication site transfer for the i.MX RT1024 associated with this notification, from the current SMIC8, Shanghai, China Wafer Fabrication site to the SMICB2, Beijing, China Wafer Fabrication site.

Wafer Fabrication site transfer was successfully qualified adhering to NXP specifications.

i.MX RT1024 maskset revision 1N87V (from 0N87V) which has been qualified with new part numbers MIMXRT1024xxxxB. Datasheet update to Revision 2 with new part number added. The Datasheet can be found from below NXP website:

https://www.nxp.com/products/processors-and-microcontrollers/arm-microcontrollers/i-mx-rt-crossover-mcus/i-mx-rt1024-crossover-mcu-with-arm-cortex-m7-core:i.MX-RT1024?tab=Documentation_Tab

The new mask revision has the below improvement:

Fixed ERR050101 USB: Endpoint conflict issue in device mode. An endpoint conflict occurs when the USB is working in device mode during an isochronous communication.

Due to the unprecedented supply constraints within the Semiconductor Industry and existing backlog profile, new orders must be placed on the new replacement parts immediately. There are cases that existing backlog will need to be migrated to the replacement parts. NXP will work with each customer to manage those transitions.

Please contact your NXP sales or marketing representative for additional information.

Reason

SMIC8, Shanghai, China wafer Fabrication site will cease production for 40nm technology production line and need transfer the products to internal SMICB2 Wafer Fabrication site. The Qualification of SMICB2, Beijing, China Wafer fabrication site is required for manufacturing flexibility and customer supply assurance.

The release of i.MX RT1024 new maskset 1N87V fixed ERR050101 USB: Endpoint conflict issue in device mode.

Identification of Affected Products

Replacement part type created, see Parts Affected list

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Sep 01, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Apr 20, 2022.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Fubin Yao
Position	Product Engineer
e-mail address	Fubin.yao@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New Orderable Part#	12NC New	Product Type New	Product Description New	Product Line
MIMXRT1024DAG5A	935416163557	MIMXRT1024DAG5A	i.MXRT1024	(L)QFP144	SOT486-2	RFS	No	MIMXRT1024DAG5B	935428157557	MIMXRT1024DAG5B	i.MXRT1024 RevB	BLM1
MIMXRT1024CAG4A	935416162557	MIMXRT1024CAG4A	i.MXRT1024	(L)QFP144	SOT486-2	RFS	No	MIMXRT1024CAG4B	935428156557	MIMXRT1024CAG4B	i.MXRT1024 RevB	BLM1